L Number	Hits	Search Text	DB	Time stamp
1	240	(427/335).CCLS.	USPAT;	2003/10/22 13:17
		·	US-PGPUB;	
1		·	EPO; JPO;	ĺ
]			DERWENT; IBM TDB	
2	475	(407/336) 0018	USPAT;	2003/10/22 13:12
4	4/5	(427/336).CCLS.	US-PGPUB;	2003/10/22 13:12
			EPO; JPO;	!
}			DERWENT;	1
			IBM TDB	
3 1	75	(((427/335).CCLS.) or ((427/336).CCLS.))	USPĀT;	2003/10/22 13:18
		and (resist or photoresist or novolac)	US-PGPUB;	
į į		·	EPO; JPO;	i i
j J			DERWENT;	ļ
	407	(407/340) GGT G	IBM_TDB USPAT;	2003/10/22 13:18
4	487	(427/340).CCLS.	US-PGPUB;	2003/10/22 13:10
}			EPO; JPO;	i
}			DERWENT;	1
			IBM TDB	
5	99	(((427/335).CCLS.) or ((427/336).CCLS.) or	USPĀT;	2003/10/22 13:18
		((427/340).CCLS.)) and (resist or	US-PGPUB;	
		photoresist)	EPO; JPO;	
j ļ			DERWENT;]
		///A07/22E) COTC) om //A07/22E) COTC) om	IBM_TDB USPAT;	2003/10/22 13:19
6	3	(((427/335).CCLS.) or ((427/336).CCLS.) or ((427/340).CCLS.)) and (solvent same	US-PGPUB;	2003/10/22 13:19
		PGMEA)	EPO; JPO;	
		· ·	DERWENT;	1
			IBM TDB	
- 1	2	"6355198"	USPĀT;	2003/10/22 11:48
		·	US-PGPUB;	
1			EPO; JPO;	
,			DERWENT;	ļ
	4	0000 461607 NDTN	IBM_TDB DERWENT	2003/09/24 15:37
~	1 0	2002-461607.NRAN. 6355198.URPN.	USPAT	2003/09/24 15:37
_	25	(polymer and mold and capillary).clm.	USPAT;	2003/10/21 13:40
ì	23	(polymer and mora and superiory) term.	US-PGPUB;	2000, 20, 22
			EPO; JPO;	
ĺ			DERWENT;	ĺ
			IBM_TDB]
-	252	(polymer and mold and pattern).clm.	USPAT;	2003/09/24 15:42
1)		US-PGPUB;	1
			EPO; JPO; DERWENT;	
1	}		IBM TDB	1
_	46	(polymer and mold and (heat adj	USPAT;	2003/09/24 15:43
		treat\$4)).clm.	US-PGPUB;	
'	!	,	EPO; JPO;	. 1
1			DERWENT;	1
]			IBM_TDB	1
! -	41	((polymer or resin) and mold and	USPAT;	2003/09/24 15:43
}	}	capillary).clm.	US-PGPUB;	
			EPO; JPO; DERWENT;	
1	}		IBM TDB	1
_	0	("(capillaryandmicromolding).ti.").PN.	USPAT;	2003/09/24 15:44
[,, .,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB;	
] !			EPO; JPO;	j
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]			IBM_TDB	
[-	2	(capillary and micromolding).ab.	USPAT;	2003/09/24 15:45
]			US-PGPUB;	1
			EPO; JPO;	
1			DERWENT; IBM TDB	1
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} -	3	(capillary and micromolding).ti.	USPAT; US-PGPUB;	2003/09/24 15:50
			EPO; JPO;	
1	1		DERWENT;	
_	9	(micromolding).ti.	IBM_TDB USPAT;	2003/09/24 15:45
		(MICIOMOLALIS). CI.	US-PGPUB;	2000,00,21
			EPO; JPO;	
	1		DERWENT; IBM TDB	
) <u> </u>	22	(micromolding).ab.	USPAT;	2003/09/24 15:45
1	(US-PGPUB;	
	}		EPO; JPO; DERWENT;	
			IBM_TDB	
-	20638	((polymer or resin) and molding).ti.	USPAT; US-PGPUB;	2003/09/24 15:47
	1	`	EPO; JPO;	
	Ì	•	DERWENT;	
	293	whitesides.in.	IBM_TDB USPAT;	2003/09/24 15:48
] _	293	whitesides.in.	US-PGPUB;	2003/09/24 13.40
}			EPO; JPO;	
			DERWENT; IBM TDB	
-	45	whitesides.in. and printing	USPAT;	2003/09/24 15:52
))	<u> </u>	US-PGPUB;	}
		·	EPO; JPO; DERWENT;	
1	1		IBM_TDB	
-	22.	(microcontact adj printing).ti.	USPAT;	2003/10/17 15:27
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	3.51	whitesides.in. and (polymer or resin)	IBM_TDB USPAT;	2003/09/24 15:50
_	151	whitesides.in. and (polymer of resin)	US-PGPUB;	2003/09/24 13.30
	1.		EPO; JPO;	
1	1		DERWENT; IBM TDB	,
-	10	(capillary and molding).ti.	USPAT;	2003/09/24 15:50
	,		US-PGPUB;	
}	ł		EPO; JPO; DERWENT;	
j	}		IBM TDB	
-	10	whitesides.in. and (PGMEA or novolac)	USPĀT;	2003/10/21 11:49
	1		US-PGPUB; EPO; JPO;	}
)	}		DERWENT;	
	100	(216/44) CCTS	IBM_TDB USPAT;	2003/09/24 15:58
-	102	(216/44).CCLS.	US-PGPUB;	2003/03/24 13:38
}			EPO; JPO;	
			DERWENT; IBM TDB	
-	738	(216/2).CCLS.	USPAT;	2003/09/24 15:56
}	}		US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	34	("3873359" "3873360" "3900614"	USPĀT	2003/09/24 15:57
		"4098922" "4100037" "4192764" "4258001" "4322457" "4472458"		
		"4508755" "4555414" "4637904"		
		"4690715" "4710401" "4728591" "4802951" "4869778" "4959252"	+	
ļ		"4802951" "4869778" "4959252" "5073495" "5079600" "5087510"	J	
		"5141785" "5170461" "5227474"		
1		"5259926" "5345869" "5385116" "5393401" "5439829" "5471455"		
		"5484324" "5512131" "5620850"	}	
	L	"5976826").PN.		

Page 2

US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:58
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1 - 1 - ATM 1 (716733) (318 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	2003/09/24 16:01
- 479 (216/33).CCLS. USPAT; US-PGPUB;	
EPO; JPO;	j
DERWENT;	
IBM_TDB	
- 1052 (216/41).CCLS. USPĀT;	2003/09/24 16:02
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	2003/09/24 16:03
- 1938 (264/259).CCLS. USPAT; US-PGPUB;	2003/09/24 ID:03
EPO; JPO;	
DERWENT;	
IBM TDB	
- 1431 (264/299).CCLS. USPAT;	2003/09/24 16:04
US-PGPUB;	
EPO; JPO;	(
DERWENT;	}
IBM_TDB	
55, (201,000,0020.	2003/09/24 16:04
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM_TDB	2003/09/24 16:04
- 532 (264/331.11).CCLS. USPAT; US-PGPUB;	2000/00/24 10:04
EPO; JPO;	
DERWENT;	
IBM TDB	
- 829 (\$5contact adj print\$3).ti. USPĀT;	2003/10/17 15:28
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	2003/10/17 15:28
- 52 (\$5contact adj print\$3).ti. and polymer USPAT; US-PGPUB;	7003/10/11 13:78
EPO; JPO;	
DERWENT;	
IBM TDB	
- 6 (\$5contact adj print\$3).ti. and capillary USPAT;	2003/10/17 15:29
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	2002/10/17 15:00
- 4 (\$5contact adj print\$3).ti. and capillary USPAT;	2003/10/17 15:29
and polymer US-PGPUB; EPO; JPO;	
DERWENT;	
IBM TDB	
- 10 whitesides.in. and (novolac) USPAT;	2003/10/21 11:49
US-PGPUB;	·
EPO; JPO;	
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IBM TDB	0000/10/10/10/10/10/10/10/10/10/10/10/10
- 1436 (polymer and capillary).ab. USPAT;	2003/10/21 11:51
US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
- 2 (polymer and capillary).ab. and PGMEA USPAT;	2003/10/21 11:51
US~PGPUB;	
EPO; JPO;	
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US-PGPUB; EPO; JPO; DERWENT; IBM_TDB Label{eq:DEM_TDB} US-PGPUB; EPO; JPO; DERWENT; USPAT;	2003/10/21 11:52
EPO; JPO; DERWENT; IBM_TDB Label{eq:DEM_TDB} DEM_TDB USPAT;	
IBM_TDB USPAT;	
145 photoresist with PGMEA USPAT;	
110 1	2003/10/21 18:55
US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
	2003/10/21 16:21
US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
	2003/10/21 13:24
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 0 micromoulding near3 capillaries USPAT;	2003/10/21 13:25
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 46 micromolding near3 capillaries USPAT;	2003/10/21 13:39
US-PGPUB; EPO; JPO;	
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o (minute)	2003/10/21 13:33
(novolac) US-PGPUB; EPO; JPO;	
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	2003/10/21 13:34
(photoresist) US-PGPUB; EPO; JPO;	
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IBM TDB	2002/10/01 12:10
7 (micromolding near3 capillaries) and USPAT; (inorganic with mold) US-PGPUB;	2003/10/21 13:46
EPO; JPO;	
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IBM_TDB	2003/10/21 13:40
US-PGPUB;	2000/10/21 10:40
EPO; JPO;	
DERWENT; IBM TDB	
	2003/10/21 13:54
US-PGPUB;	
EPO; JPO;	
DERWENT;	
	2003/10/21 13:57
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 399 ("sio.sub.2") with mold USPAT;	2003/10/21 13:57
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM_TDB	
- 10 (silicon adj dioxide) with (mold and USPAT;	2003/10/21 13:55
(porous or porosity)) US-PGPUB; EPO; JPO;	
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			TIODAM	10000/10/01 12:55
~	19	("sio.sub.2") with (mold and (porous or porosity))	USPAT; US-PGPUB;	2003/10/21 13:55
		porosity),	EPO; JPO;	J
			DERWENT;	
ĺ			IBM TDB	1
_	7	(silicon adj dioxide) adj mold	USPAT;	2003/10/21 13:57
)			US-PGPUB;	j j
		,	EPO; JPO;	
ĺ			DERWENT;	(
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-	18	("sio.sub.2") adj mold	USPAT;	2003/10/21 13:57
			US-PGPUB;	ì
ļ			EPO; JPO; DERWENT;	
}			IBM TDB	!
_	2	("6329211").PN.	USPAT;	2003/10/21 14:32
		(0023212 / 1111.	US-PGPUB;	2000, 20, 22 21.02
ĺ			EPO; JPO;	Į i
			DERWENT;	}
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-	2	photoresist with novolac with PGMEA	USPAT;	2003/10/21 16:22
({		US-PGPUB;	
}	}		EPO; JPO;	}
J j	J		DERWENT;	
	5	photoresist same novolac same PGMEA	IBM_TDB USPAT;	2003/10/21 17:09
	1	Miororestsc same novotac same tamba	US-PGPUB;	2003/10/21 17:09
	}		EPO; JPO;	}
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			IBM TDB	
-	3090	damascene and photoresist	USPAT:	2003/10/21 17:10
})		US-PGPUB;	
			EPO; JPO;]
!			DERWENT;	
Ì	670		IBM_TDB	2002/10/21 17:14
_	679	damascene and photoresist and copper and wiring and pattern	USPAT; US~PGPUB;	2003/10/21 17:14
,	}	wiring and pattern	EPO; JPO;	j
			DERWENT;	
i	i		IBM TDB	ĺ
-	9397	copper adj clad\$4	USPĀT;	2003/10/21 17:13
]			US-PGPUB;)
			EPO; JPO;	
ĺ			DERWENT;	(
į	*****	107.5/107.007.0	IBM_TDB	0000/10/01 17 15
-	1101	(216/13).CCLS.	USPAT;	2003/10/21 17:15
	'		US-PGPUB; EPO; JPO;	
ļ			DERWENT;	·
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	335	((216/13).CCLS.) and (resist or	USPAT;	2003/10/21 17:17
ļ		photoresist) and copper	US-PGPUB;	
[EPO; JPO;	1
	i		DERWENT;	,
ļ			IBM_TDB	
-	244	((216/13).CCLS.) and (resist or	USPAT;	2003/10/21 17:18
		photoresist) and pattern with (wiring or	US-PGPUB;	
·	'	conduct\$3)	EPO; JPO; DERWENT;	
			IBM TDB	
~	345	photoresist with (novolac adj resin)	USPAT:	2003/10/21 18:15
	313	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	[
ł	1		EPO; JPO;	· · · · · · · · · · · · · · · · · · ·
]		DERWENT;	
ļ			IBM_TDB	
~	15	(photoresist same (novolac adj resin)) and	USPAT;	2003/10/21 18:27
	İ	PGMEA	US-PGPUB;	
ļ			EPO; JPO;	
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	10	photoresist and (PGMEA with evaporat\$3)	USPAT; US-PGPUB;	2003/10/21 18:23
	35	photoresist and (PGMEA same evaporat\$3)	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/21 18:36
-	36	(photoresist same novolac) and PGMEA	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/21 18:27
-	38	(photoresist same novolac\$1) and PGMEA	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/21 18:34
-	107	photoresist and (PGMEA same heat\$3)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:28
-	23	photoresist and (PGMEA with heat\$3)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/21 18:29
-	27	(photoresist same fluidiz\$3) and (evaporat\$3 or vapor\$5)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:35
-	15	PGMEA same evaporat\$3 same resin	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/10/21 18:42
_	39	(PGMEA or polymer or resin or solvent) and (sealed adj vessel) and photoresist	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:46
	1720	(PGMEA or polymer or resin or solvent) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:46
_	22	((PGMEA or polymer or resin or solvent) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)).ab.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:48
-	484	(solvent and (polymer or photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:52
-	258	(solvent and (polymer or photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/21 18:50
_	. 8	(solvent and (polymer and photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 18:51

T	116	(solvent same vapor) same diffusion same	USPAT;	2003/10/21 18:53
		(resin or polymer or photoresist)	US-PGPUB;	1
[(1000m of posymer or product,	EPO; JPO;	
}	}		DERWENT;	}
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	670	labet and Down	USPAT:	2003/10/21 18:55
-	679	photoresist and PGMEA		2003/10/21 18:55
}	}		US-PGPUB;	Ì
}			EPO; JPO;	}
ļ		· ·	DERWENT;	
1 .		,	IBM_TDB	.
} ~	166	photoresist and PGMEA and (diffusion)	USPAT;	2003/10/21 19:13
ļ	Į.		US-PGPUB;	
<u> </u>			EPO; JPO;	
1	ŕ		DERWENT;	{
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\ _	9	(fluidizing and polymer).ti.	USPAT;	2003/10/21 19:14
[1	(11444201119 think polymory)	US-PGPUB;	(
}	ì		EPO; JPO;	1
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[0	(fluidizing and photoresist).ti.	USPAT;	2003/10/21 19:14
-	0	(IIIIIAIZING and photoresist).ti.	1	2003/10/21 19:14
}	-		US-PGPUB;	1
ļ			EPO; JPO;	
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	534	(solvent and photoresist).ti.	USPAT;	2003/10/21 19:23
[US-PGPUB;	
ĺ		, ,	EPO; JPO;	\
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ļ	J		IBM TDB]
ì -	4	(solvent and photoresist and vapor).ti.	USPAT;	2003/10/21 19:25
			US-PGPUB;	1
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ì			IBM TDB	
{ - -	12	(solvent and photoresist and vapor).ab.	USPAT;	2003/10/21 19:27
1		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB	
 _	20	(solvent and resist and vapor).ab.	USPAT;	2003/10/22 11:14
}] 20	(Solvette and restrict and vapor). as:	US-PGPUB] 2000, 20, 22 32.21
_	31	(solvent and (resist or photoresist) and	USPAT;	2003/10/22 10:55
ĺ		(chamber or vessel)).ab.	US-PGPUB	2000, 20, 22 20.00
}	19	(solvent and resist and (chamber or	USPAT;	2003/10/22 10:57
ļ	}	vessel)).ab.	US-PGPUB	2003, 10, 22 10.3.
l _	43	(solvent and resist and (absorb\$3 or	USPAT;	2003/10/22 10:58
ì	43	diffus\$3 or evaporat\$3 or permeat\$3)).ab.		2003/10/22 10:38
}			US-PGPUB	0000 (10 (00 11 00
] ~	83	(solvent and resist).ab. and PGMEA	USPAT;	2003/10/22 11:00
		(- 1	US-PGPUB	2002/10/20 11 12
-	532	(solvent and resist).ab.	USPAT;	2003/10/22 11:10
1			US-PGPUB	0000/10/22 11 11
J ~~	23	(("3737499") or ("3597257") or ("3539381")	USPAT;	2003/10/22 11:11
		or ("3339526") or ("2294479") or	US-PGPUB;	
Ĭ	í	("2138578")).PN.	EPO; JPO;	
ļ	ł		DERWENT;	1
	J		IBM TDB	}
-	7	("0243200" "2138578" "2294479"	USPĀT	2003/10/22 11:13
Ì	("3339526" "3539381" "3597257"	1	1
	1	"3737499").PN.	1	}
_	16		USPAT	2003/10/22 11:13
_	23	(solvent and resist and (chamber or vessel	USPAT;	2003/10/22 11:15
{	1	or container)).ab.	US-PGPUB	1
l	37	(solvent and (photoresist or resist) and	USPAT;	2003/10/22 11:18
l	1	(chamber or vessel or container)).ab.	US-PGPUB	1
 _	4	(("5374693") or ("5614349")).PN.	USPAT;	2003/10/22 11:18
	(, , , _ , - , - , - , - , - , - , , , - , , , , - , , , - , , , - , , , - ,	US-PGPUB;	-515. 20/22 22.10
	1		EPO; JPO;	1
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_ `	10	(("4315985") or ("6143412") or ("6004444")	USPAT;	2003/10/22 11:48
	1	or ("5965237")).PN.	US-PGPUB;	
	}	01 \ 0300231 1.12N.	EPO; JPO;	· ·
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L	1	<u> </u>	IBM TDB	L
	story 10	0/22/03 1:22:45 PM Page 7		. — <u>_ — . — . — . — . — . — . — . — . — . — </u>

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